

Abstract of the Disclosure

Methods for the preparation of multilayered resists are described. A first layer of photoresist is deposited onto a substrate. First portions of the first layer are exposed to a first dose of radiant energy. A second layer of photoresist is deposited at atop the first layer and second portions of the second layer are exposed to a second varied dose of radiant energy. The dose is modulated over different portions of a layer to preferentially enhance development within the interior of the structure to reduce total development times.

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